

# **2021 37th Semiconductor Thermal Measurement, Modeling & Management Symposium (SEMI-THERM 2021)**

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As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 38** will begin accepting abstracts during the summer (deadline is September 15, 2021). We welcome your submissions! Visit us at [www.semi-therm.org](http://www.semi-therm.org).

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